



IEEE

IEC 61445

Edition 1.0 2012-06

INTERNATIONAL STANDARD

IEEE Std 1445™

Digital Test Interchange Format (DTIF)

INTERNATIONAL
ELECTROTECHNICAL
COMMISSION

PRICE CODE **XD**

ICS 25.040; 35.060

ISBN 978-2-83220-105-3

Warning! Make sure that you obtained this publication from an authorized distributor.

Contents

1.	Overview.....	1
1.1	Scope.....	1
1.2	Purpose.....	1
1.3	Application.....	1
2.	References.....	2
3.	Definitions and acronyms	2
3.1	Definitions.....	2
3.2	Acronyms	4
4.	Data organization overview of the DTIF standard environment.....	4
4.1	UUT Model Group.....	5
4.2	Stimulus and Response Group.....	5
4.3	Fault Dictionary Group	5
4.4	Probe Group	5
5.	File specifications.....	6
5.1	HEADER file	7
5.2	STIMULUS file	9
5.3	PO_RESPONSE file	10
5.4	PI_NAMES file	11
5.5	PO_NAMES file	12
5.6	MAIN_MODEL file.....	13
5.7	COMPONENT_TYPE file.....	14
5.8	USER_NODE file	15
5.9	INPUT_PIN_NAMES file	16
5.10	OUTPUT_PIN_NAMES file	17
5.11	NEAR_FROMS_POINTERS file	18
5.12	NEAR_FROMS file	19
5.13	EVENT file	20
5.14	SETTLED_STATE_ONLY file.....	22
5.15	SETTLED_STATE_&_PULSES file.....	23
5.16	NODE_SOURCE file.....	25
5.17	STEPS file.....	26
5.18	F.D._POPATS file.....	27
5.19	F.D._FAULT_SIGNATURES file	28
5.20	F.D._PRINT_STRINGS file	30
5.21	TRISTATE_FROMS_POINTERS file.....	32
5.22	TRISTATE_FROMS file	33
5.23	PSEUDOPI_NAMES file	34
5.24	TIMING_SETS file.....	35
5.25	TIMING_PER_PATTERN file	37
5.26	PHASE_CONNECTIONS file.....	38
5.27	AUXILIARY_PIN_NAMES file	39
5.28	PI_FORMATS file	40
5.29	FORMAT_ATTRIBUTES file	41

5.30 F.D. _CROSS_REFERENCE file	42
5.31 PROBETAG_DEFINITIONS file	43
5.32 PROBETAG_ASSIGNMENTS file	45
5.33 BURSTS file	46
5.34 STIMULUS_TEXT file	47
5.35 NODE_NAMES file	48
5.36 EVENTS_INIT file	49
5.37 EQUIV_FAULTS file	51
5.38 PROBE_DETECTION file	52
5.39 F.D._EQUIV_SETS file	53
6. Conformance	54
6.1 End-to-end test	54
6.2 Diagnostic test using fault dictionary	54
6.3 Diagnostic test using probe	56
Annex A (informative) Implementation overview	59
Annex B (informative) DTIF dependency diagrams	61
Annex C (informative) Example circuit	66
Annex D (informative) IEEE List of Participants	100

Digital Test Interchange Format (DTIF)

FOREWORD

- 1) The International Electrotechnical Commission (IEC) is a worldwide organization for standardization comprising all national electrotechnical committees (IEC National Committees). The object of IEC is to promote international co-operation on all questions concerning standardization in the electrical and electronic fields. To this end and in addition to other activities, IEC publishes International Standards, Technical Specifications, Technical Reports, Publicly Available Specifications (PAS) and Guides (hereafter referred to as "IEC Publication(s)"). Their preparation is entrusted to technical committees; any IEC National Committee interested in the subject dealt with may participate in this preparatory work. International, governmental and non-governmental organizations liaising with the IEC also participate in this preparation.

IEEE Standards documents are developed within IEEE Societies and Standards Coordinating Committees of the IEEE Standards Association (IEEE-SA) Standards Board. IEEE develops its standards through a consensus development process, which brings together volunteers representing varied viewpoints and interests to achieve the final product. Volunteers are not necessarily members of IEEE and serve without compensation. While IEEE administers the process and establishes rules to promote fairness in the consensus development process, IEEE does not independently evaluate, test, or verify the accuracy of any of the information contained in its standards. Use of IEEE Standards documents is wholly voluntary. IEEE documents are made available for use subject to important notices and legal disclaimers (see <http://standards.ieee.org/IPR/disclaimers.html> for more information).

IEC collaborates closely with IEEE in accordance with conditions determined by agreement between the two organizations.

- 2) The formal decisions of IEC on technical matters express, as nearly as possible, an international consensus of opinion on the relevant subjects since each technical committee has representation from all interested IEC National Committees. The formal decisions of IEEE on technical matters, once consensus within IEEE Societies and Standards Coordinating Committees has been reached, is determined by a balanced ballot of materially interested parties who indicate interest in reviewing the proposed standard. Final approval of the IEEE standards document is given by the IEEE Standards Association (IEEE-SA) Standards Board.
- 3) IEC/IEEE Publications have the form of recommendations for international use and are accepted by IEC National Committees/IEEE Societies in that sense. While all reasonable efforts are made to ensure that the technical content of IEC/IEEE Publications is accurate, IEC or IEEE cannot be held responsible for the way in which they are used or for any misinterpretation by any end user.
- 4) In order to promote international uniformity, IEC National Committees undertake to apply IEC Publications (including IEC/IEEE Publications) transparently to the maximum extent possible in their national and regional publications. Any divergence between any IEC/IEEE Publication and the corresponding national or regional publication shall be clearly indicated in the latter.
- 5) IEC and IEEE do not provide any attestation of conformity. Independent certification bodies provide conformity assessment services and, in some areas, access to IEC marks of conformity. IEC and IEEE are not responsible for any services carried out by independent certification bodies.
- 6) All users should ensure that they have the latest edition of this publication.
- 7) No liability shall attach to IEC or IEEE or their directors, employees, servants or agents including individual experts and members of technical committees and IEC National Committees, or volunteers of IEEE Societies and the Standards Coordinating Committees of the IEEE Standards Association (IEEE-SA) Standards Board, for any personal injury, property damage or other damage of any nature whatsoever, whether direct or indirect, or for costs (including legal fees) and expenses arising out of the publication, use of, or reliance upon, this IEC/IEEE Publication or any other IEC or IEEE Publications.
- 8) Attention is drawn to the normative references cited in this publication. Use of the referenced publications is indispensable for the correct application of this publication.
- 9) Attention is drawn to the possibility that implementation of this IEC/IEEE Publication may require use of material covered by patent rights. By publication of this standard, no position is taken with respect to the existence or validity of any patent rights in connection therewith. IEC or IEEE shall not be held responsible for identifying Essential Patent Claims for which a license may be required, for conducting inquiries into the legal validity or scope of Patent Claims or determining whether any licensing terms or conditions provided in connection with submission of a Letter of Assurance, if any, or in any licensing agreements are reasonable or non-discriminatory. Users of this standard are expressly advised that determination of the validity of any patent rights, and the risk of infringement of such rights, is entirely their own responsibility.

International Standard IEC 61445/ IEEE Std 1445-1998 has been processed through IEC technical committee 93: Design automation, under the IEC/IEEE Dual Logo Agreement.

The text of this standard is based on the following documents:

IEEE Std	FDIS	Report on voting
IEEE Std 1445-1998	93/321/FDIS	93/328/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

The IEC Technical Committee and IEEE Technical Committee have decided that the contents of this publication will remain unchanged until the stability date indicated on the IEC web site under "<http://webstore.iec.ch>" in the data related to the specific publication. At this date, the publication will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

IEEE Standard for Digital Test Interchange Format (DTIF)

Sponsor

IEEE Standards Coordinating Committee 20 on Test and Diagnosis for Electronic Systems

Reaffirmed 9 December 2009

Approved 8 December 1998

IEEE-SA Standards Board

Reaffirmed 8 July 2004

Approved 16 November 1999

American National Standards Institute

Abstract: The information content and the data formats for the interchange of digital test program data between digital automated test program generators (DATPGs) and automatic test equipment (ATE) for board-level printed circuit assemblies are defined. This information can be broadly grouped into data that defines the following: UUT Model, Stimulus and Response, Fault Dictionary, and Probe.

Keywords: automatic test equipment (ATE), digital automated test program generator (DATPG), digital test interchange format (DTIF), Fault Dictionary data

The Institute of Electrical and Electronics Engineers, Inc.
345 East 47th Street, New York, NY 10017-2394, USA

Copyright © 1999 by the Institute of Electrical and Electronics Engineers, Inc.
All rights reserved. Published 10 March 1999. Printed in the United States of America.

IEEE Introduction

[This introduction is not part of IEEE Std 1445-1998, IEEE Standard for Digital Test Interchange Format (DTIF).]

A digital automated test program generator (DATPG) produces test pattern and diagnostic data that can be used for testing printed circuit assemblies on automatic test equipment (ATE). The use of several DATPGs, all with individual output formats, created a need for many unique post-processors to be developed and maintained for the life of the ATE. These post-processors supported the link from specific DATPGs to specific testers. The proliferation of unique formats and post-processors created logistical support problems and therefore identified a need for standardization. A DATPG and ATE independent output data format is required to limit the number of post-processors (one for each ATE) requiring life cycle support. The digital test interchange format (DTIF) was chosen because of its wide use and because it was becoming known in industry as the de facto standard.

This document provides the basis to standardize digital test information for use on ATE. The digital test information consists of the unit under test (UUT) Model information, Stimulus and Response data, Fault Dictionary data, and Probe data.

DTIF is unique from other standards such as IEEE P1450 (Draft 0.95, dated July 1998),¹ Draft Standard Test Interface Language (STIL) for Digital Test Vector Data, and IEEE Std 1029.1-1991, IEEE Standard for Waveform and Vector Exchange Specification (WAVES). STIL is being developed to standardize the output interface of existing computer-aided engineering (CAE) tools with the input interface of ATE for integrated circuit (IC) testing only. WAVES is a hardware descriptive language used for defining stimulus and response, and their associated timing for IC/board-level design. Neither STIL nor WAVES provides for board-level fault diagnostics.

A future revision of this standard will consider the use of the information model.

¹ IEEE P1450 is an IEEE authorized standards project that was not approved by the IEEE-SA Standards Board at the time this publication went to press. For information about obtaining the draft, contact the IEEE.

Digital Test Interchange Format (DTIF)

1. Overview

The digital test interchange format (DTIF) is designed to provide a mechanism for digital test data interchange independent of specific digital automated test program generators (DATPGs) and test systems. The DTIF provides a neutral database for the development and delivery of digital simulation based test program sets (TPSs). DTIF functionally supports the unit under test (UUT) Model, Stimulus and Response, Fault Dictionary, and Probe databases.

1.1 Scope

This standard defines the information content and the data formats for the interchange of digital test program data between DATPGs and automatic test equipment (ATE) for board-level printed circuit assemblies. This information can be broadly grouped into data that defines the following:

- a) UUT Model;
- b) Stimulus and Response;
- c) Fault Dictionary;
- d) Probe.

1.2 Purpose

The purpose of this standard is to provide a standard output format for test data generated by a DATPG. A DATPG produces test patterns and fault diagnostic data for ATE. This data is used in applications such as board-level assemblies where diagnostic data interchange is important.

1.3 Application

This standard is primarily intended for use by digital simulator developers/maintainers and TPS developers/maintainers.

2. References

This standard shall be used in conjunction with the following standards. When the following standards are superseded by an approved revision, the revision shall apply.

ANSI X3.4-1986 (Reaff 1997), Information Systems—Coded Character Sets—7-Bit American National Standard Code for Information Interchange (7-Bit ASCII).¹

IEEE Std 100-1996, IEEE Standard Dictionary of Electrical and Electronics Terms.²

¹ANSI publications are available from the Sales Department, American National Standards Institute, 11 West 42nd Street, 13th Floor, New York, NY 10036, USA (<http://www.ansi.org/>).

²IEEE publications are available from the Institute of Electrical and Electronics Engineers, 445 Hoes Lane, P.O. Box 1331, Piscataway, NJ 08855-1331, USA (<http://www.standards.ieee.org/>).